

Rev 1.0 27/12/22

Ultra-Fast recovery rectifier diode in bare die form

Features:

- Low leakage current
- High forward surge current capability
- Low forward voltage drop
- Robust construction
- High reliability tested grades.

Ordering Information

The following part suffixes apply:

- No suffix MIL-STD-750 /2073 Visual Inspection
- "H" MIL-STD-750 /2073 Visual Inspection+ MIL-PRF-38534 Class H LAT
- "K" MIL-STD-750 /2073 Visual Inspection
 + MIL-PRF-38534 Class K LAT

LAT = Lot Acceptance Test.

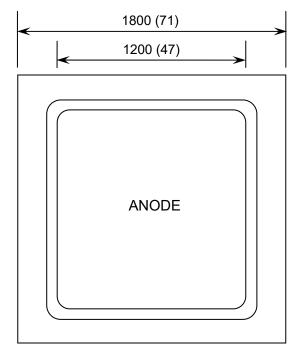
For further information on LAT process flows see below.

www.siliconsupplies.com\quality\bare-die-lot-qualification

Supply Formats:

- Default Die in Waffle Pack (100 per tray capacity)
- Sawn Wafer on Tape By specific request
- Unsawn Wafer By specific request
- With additional electrical selection By specific request

Die Dimensions in µm (mils)



CHIP BACKSIDE IS CATHODE



Mechanical Specification

Die Size (Unsawn)	1800 x 1800 70.87 x 70.87	μm mils	
Anode Pad Size	1200 x 1200 47.24 x 47.24	μm mils	
Die Thickness	220 (±20) 8.66 (±0.79)	μm mils	
Top Metal Composition	Al 7.5µm		
Back Metal Composition	Ti/Ni/Ag		





Rev 1.0 27/12/22

Absolute Maximum Ratings¹ T_J = 25°C unless otherwise stated

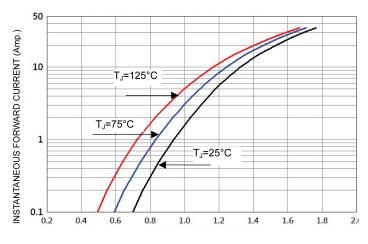
PARAMETER	SYMBOL	VALUE	UNIT	
Peak Repetitive Reverse Voltage	V_{RRM}			
Working Peak Repetitive Reverse Voltage	V _{RWM}	600	V	
DC Blocking Voltage	V _R			
RMS Reverse Voltage	V _{R (RMS)}	420	V	
Average Forward Rectified Current, T _J = 150°C	I _{F(AV)}	8	А	
Peak Repetitive Forward Current ²	I _{FM}	16	Α	
Non-Repetitive Peak Forward Surge Current ³	I _{FSM}	100	А	
Operating Junction temperature	TJ	-55 to 175	°C	
Storage Temperature Range	T _{STG}	-65 to 175	°C	

Electrical Characteristics T_J = 25°C unless otherwise stated

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
Maximum Instantaneous Forward Voltage ⁴ V _F	Ve	I _F = 8A, T _J = 25°C	-	1.30	1.50	V
	VF	I _F = 8A, T _J = 125°C	-	1.15	-	V
Maximum Instantaneous Reverse Leakage Current ⁴ I _{RM} @ V _{RR}	Inu @ Vanu	$V_{RRM} = 600V, T_J = 25^{\circ}C$	-	0.01	0.05	μА
	TRM & VRRM	V _{RRM} = 600V, T _J = 125°C	-	3	10	
Reverse Recovery Time	t _{rr}	I _F = 0.5A, I _R = 1.0A, I _{rr} = 0.25A	-	27	50	ns
Junction Capacitance	CJ	V _R = 4V, f = 1.0MHz	-	28	-	pF

^{1.} Operation above the absolute maximum rating may cause device failure. Operation at the absolute maximum ratings, for extended periods, may reduce device reliability. 2. V_R = 600V, Square Wave, 20kHz Pulse Width = 3.8ms 3. Surge applied at rated load conditions halfwave, single phase, 60Hz 4. Pulse Test: Pulse Width = 300s, Duty Cycle ≤ 2.0%

Typical Characteristics T_J = 25°C unless otherwise stated



FORWARD VOLTAGE (V)

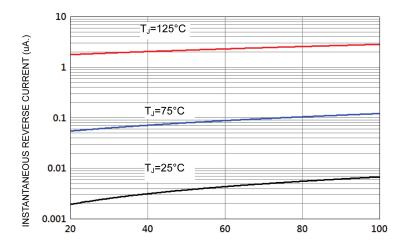
FIGURE 1. Forward Voltage Characteristics





Typical Characteristics Continued T_J = 25°C unless otherwise stated

Rev 1.0 27/12/22



PERCENT OF RATED PEAK REVERSE VOLTAGE (%)

FIGURE 2. Reverse Current Versus Reverse Voltage

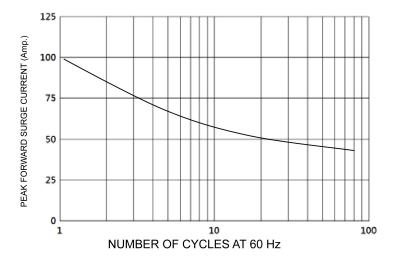


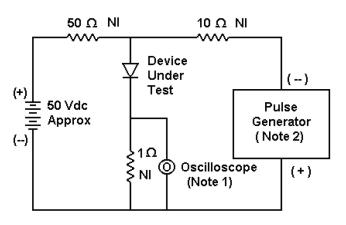
FIGURE 3. Peak Forward Surge Current Versus Cycles at 60 Hz

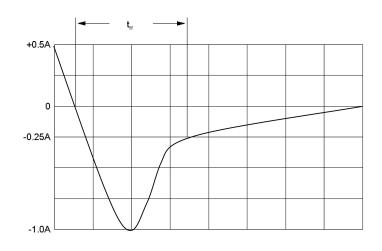




Typical Characteristics Continued T_J = 25°C unless otherwise stated

Rev 1.0 27/12/22





Notes:

- 1. Rise Time = 7 ns max. Input Impedance =1 M Ω , 22 pF
- 2. Rise Time = 10 ns max. Input Impedance = 50Ω

Set time base for 10/20 ns/cm

FIGURE 4. Reverse Recovery Time Characteristics + Test Circuit

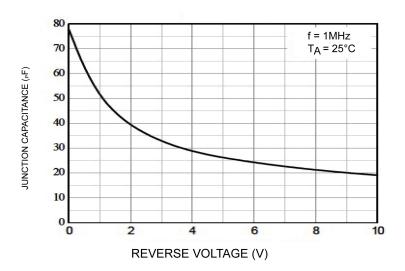


FIGURE 5. Typical Junction Capacitance

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